



# DCDB Performance and Operation Updates



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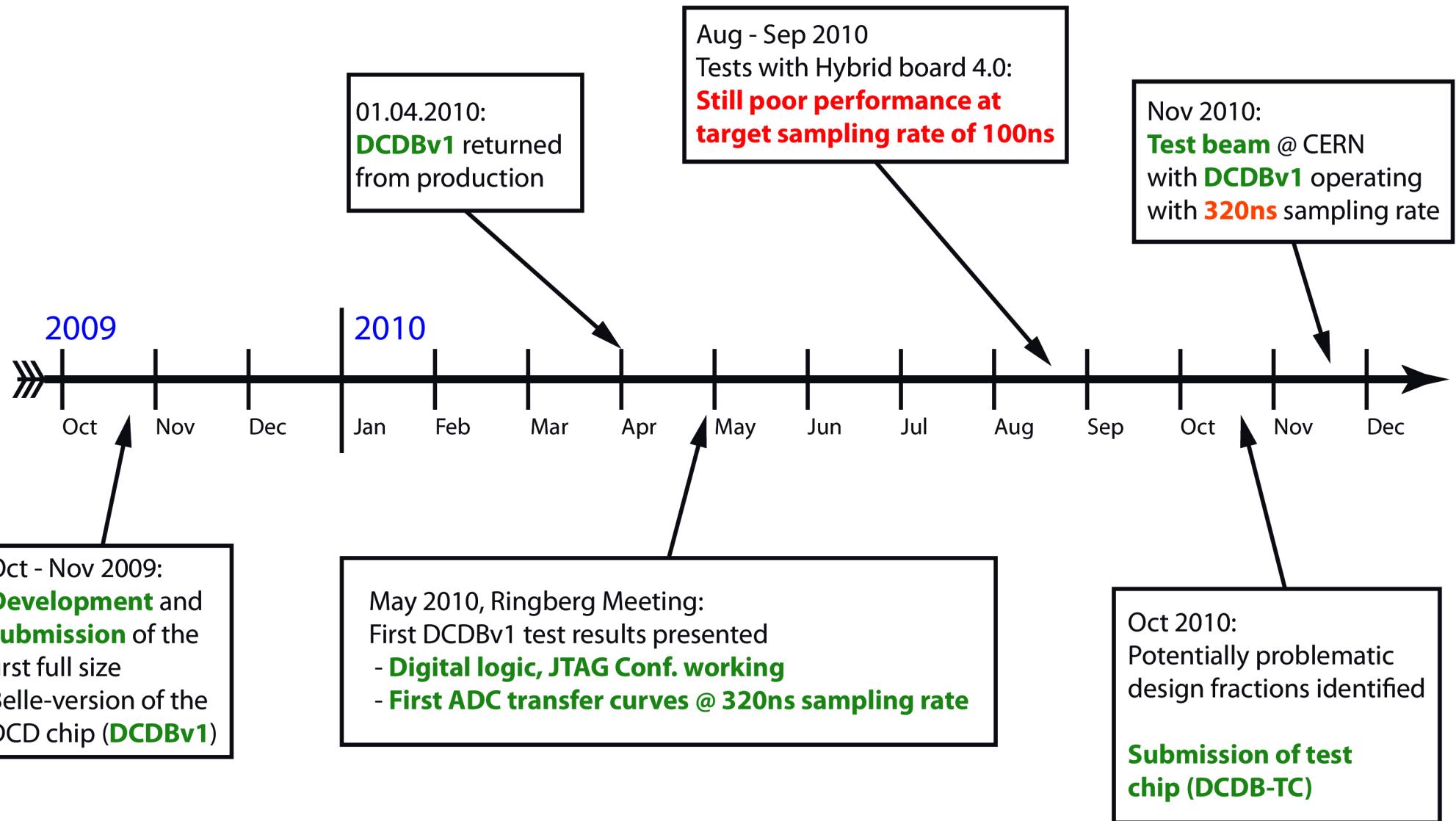
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Detectors and Applications

09.-11. May 2011

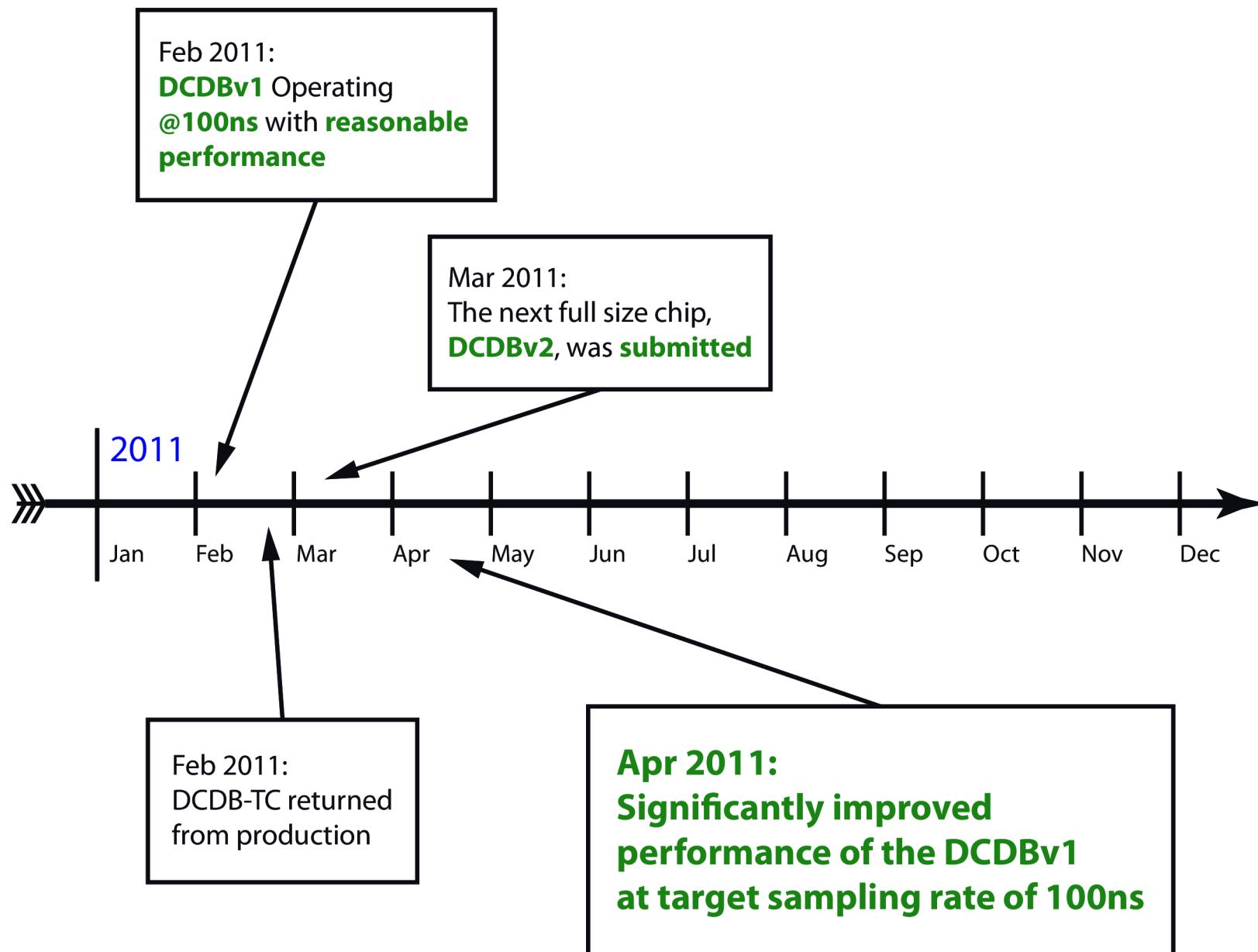
- ▶ Introduction: History of the DCDB Development
- ▶ Part I: Latest Improvements in DCDBv1 Performance
- ▶ Part II: DCDB in DEPFET Readout Operation - Dynamic Offset Compensation
- ▶ Part III: DCDB-TC Measurement Results

# Introduction: History of DCDB Development

# History of DCDB Developments (1/2)

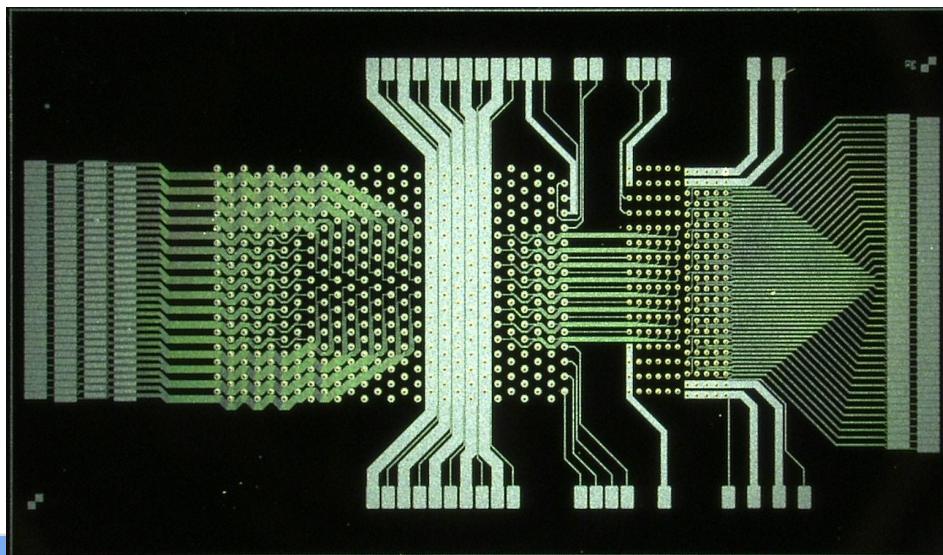
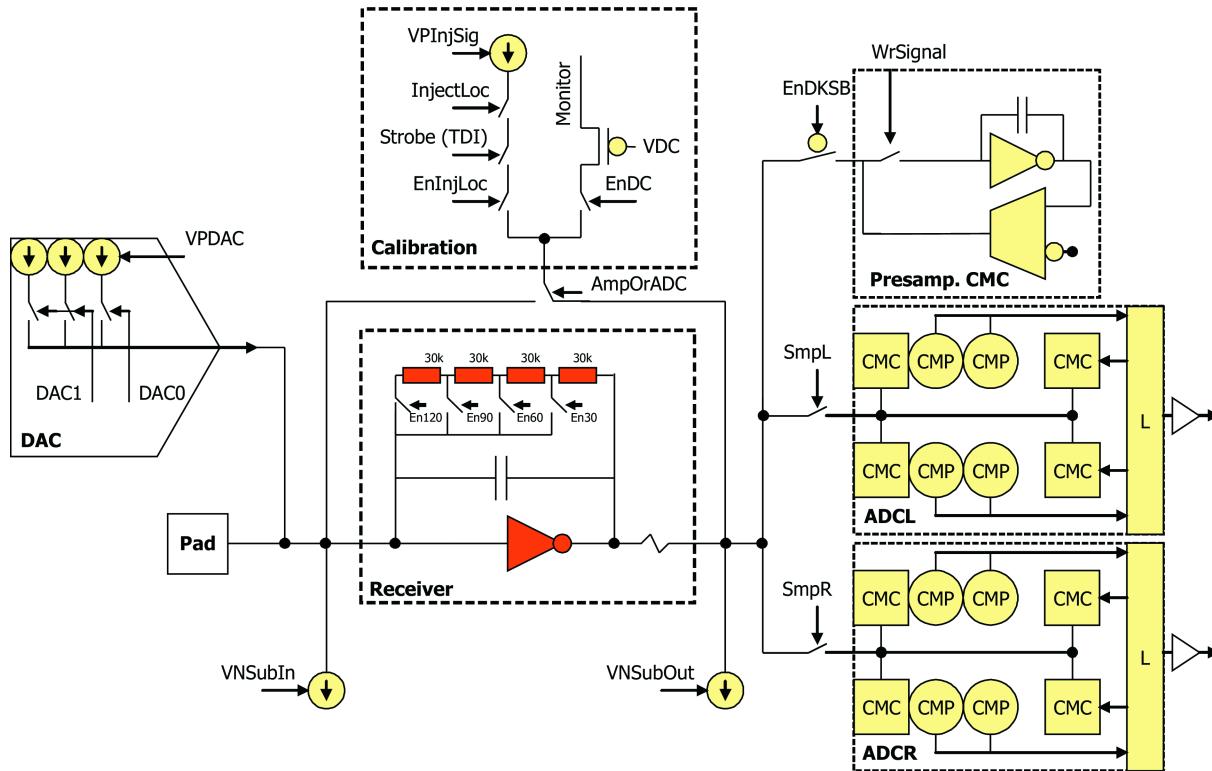


## History of DCDB Developments (2/2)



# Part I: Latest Improvements in DCDBv1 Performance

# What Led to the Improvements?



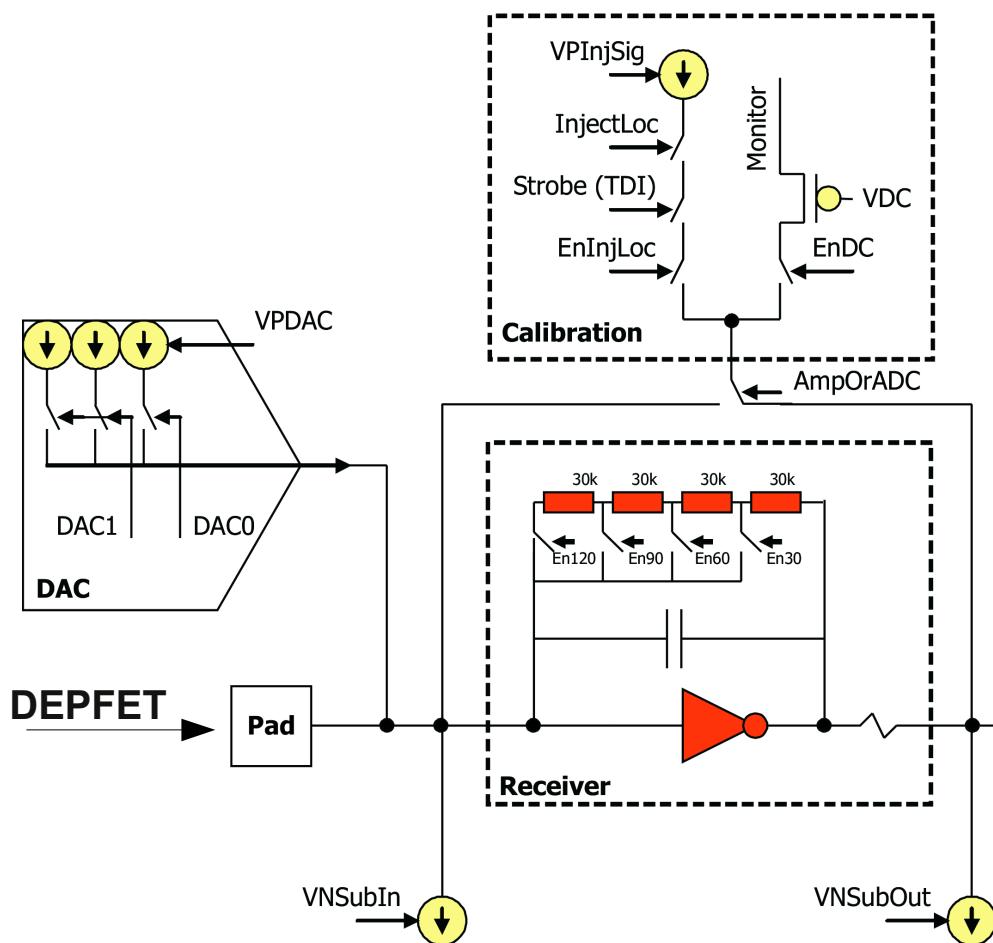
Get better understanding by detailed measurements:

- Potential of internal nodes
- TIA Characterization
- ADC's Current Memory Cell Characterization

Results:

- Suboptimal bias of TIA
- Voltage drop,  
**NOT primary inside the chip but on the WB**

# Measurement Setup

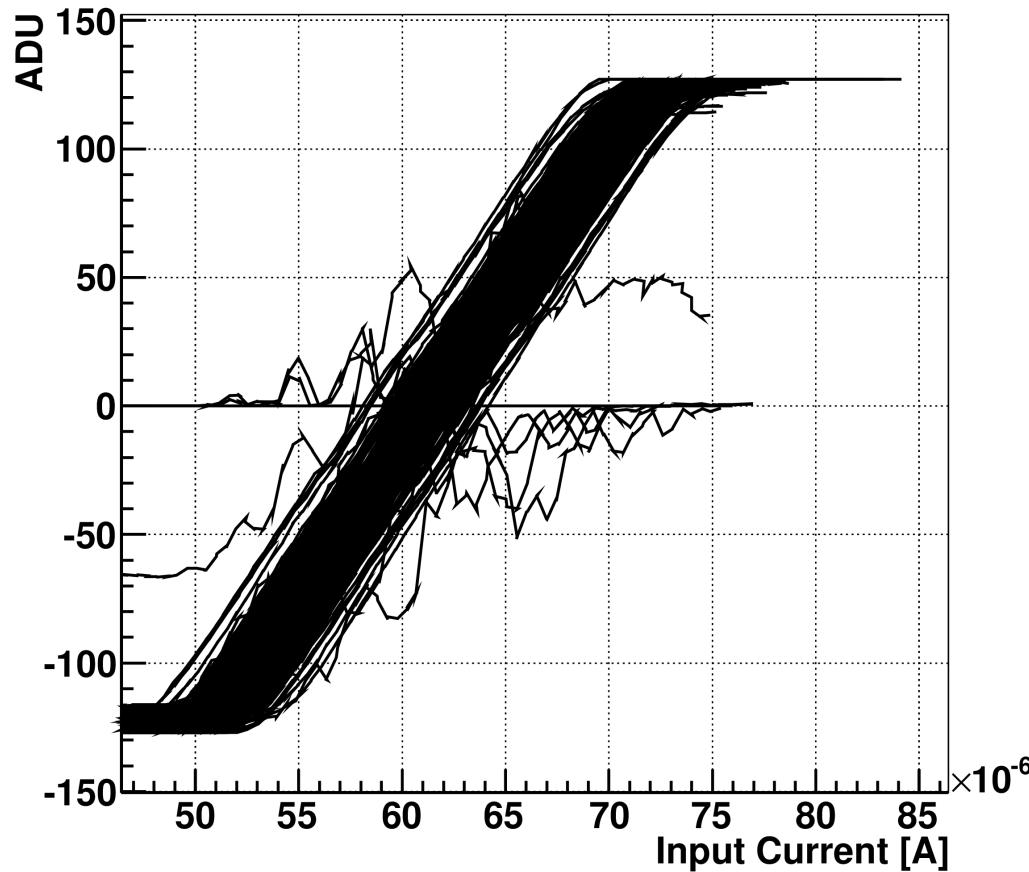


## Scenario:

- TestBeam 2010 Module used!
- Signal sampling rate : **100ns**
- Single matrix row is constantly activated.  
→ Offset Current (with variation)
- Offset is subtracted by current source **@max!**  
**(VNSubIn = 127)** → Realistic!
- Signal is generated by internal source, each calibrated via SMU.

# The DCDBv1's Current Performance (1/5)

Golden Module: All ADC Transfer Curves



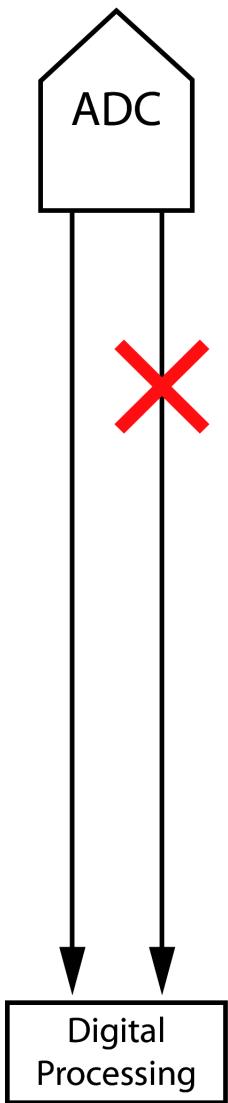
## Facts:

- 100ns sampling rate!
- Transfer curves of all 256 accessible ADCs
- Each point is the mean of 100 samples
- Here: 1ADU =  $\sim 84\text{nA}$

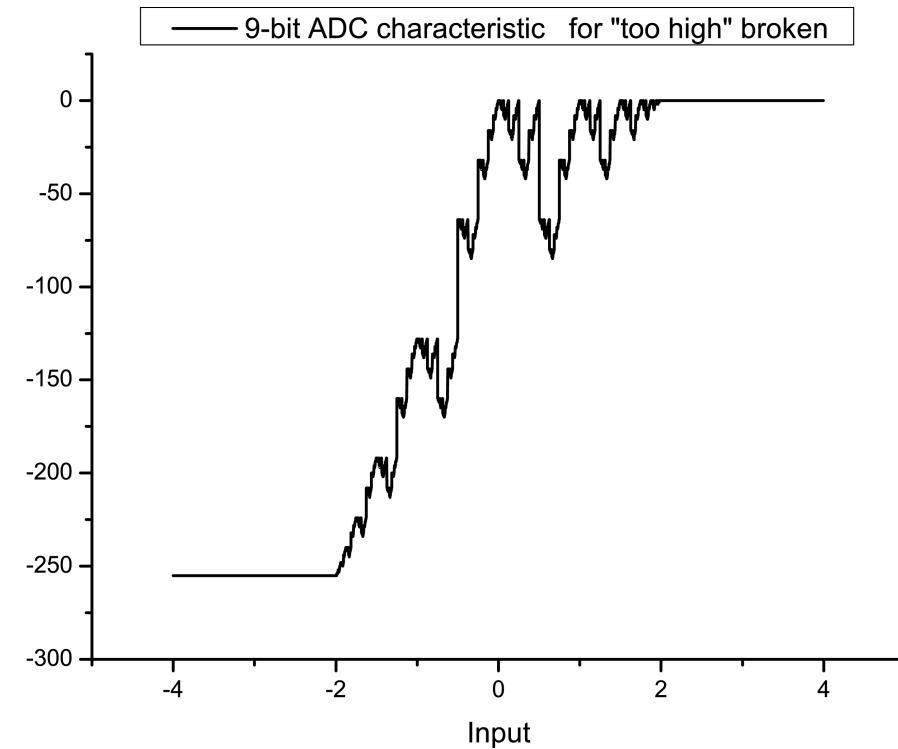
## Conclusions:

- 8 bad ADCs have already been identified during TB2010 analysis.
- Vertical dispersion:  $\sim 73\text{LSB}$ . Note: This includes DEPFET variations!

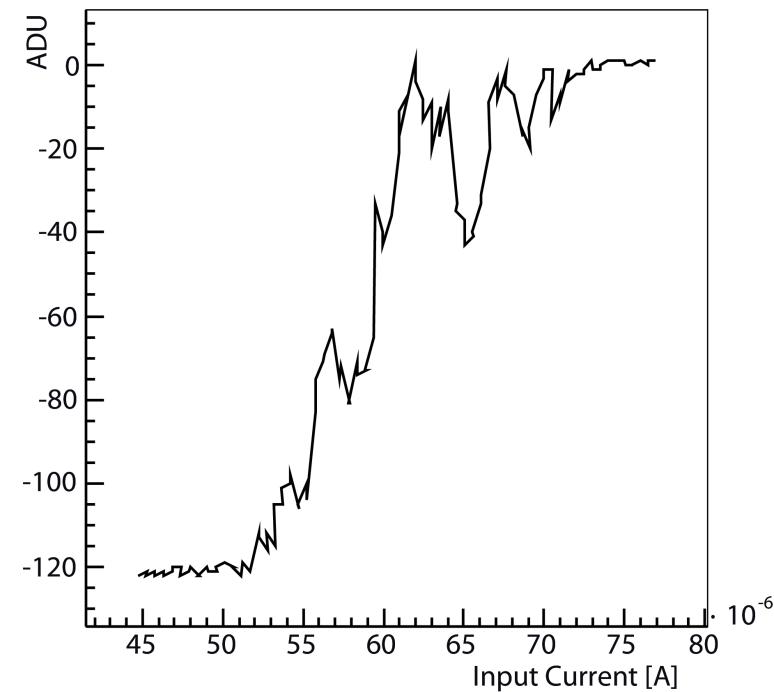
# A Propos: Bad ADCs



Simulation of the ADC transfer curve  
with one of the two lines being broken.



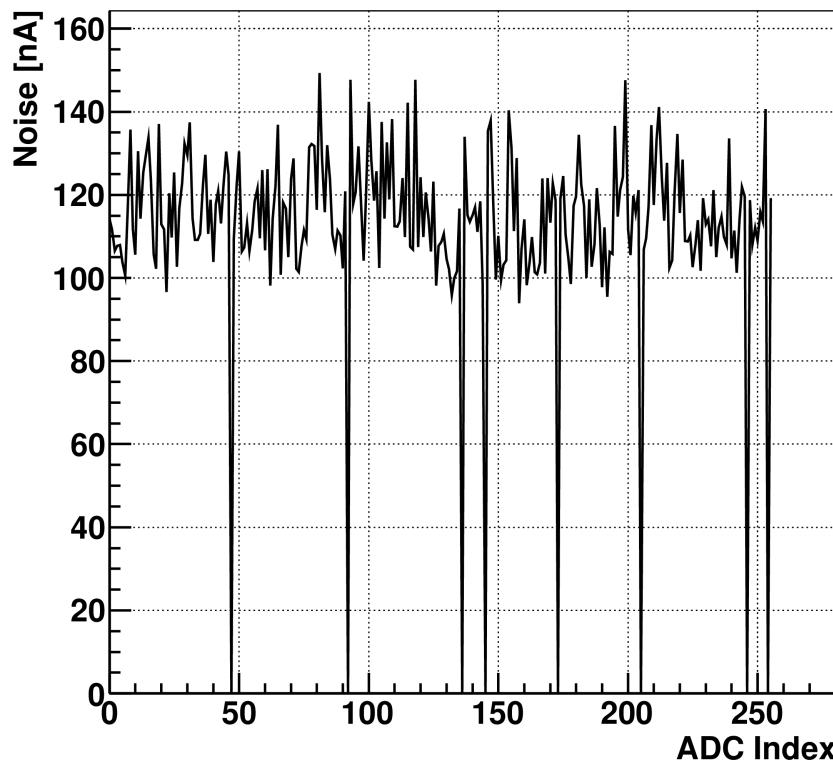
Measurement: Bad ADC's Transfer Curve



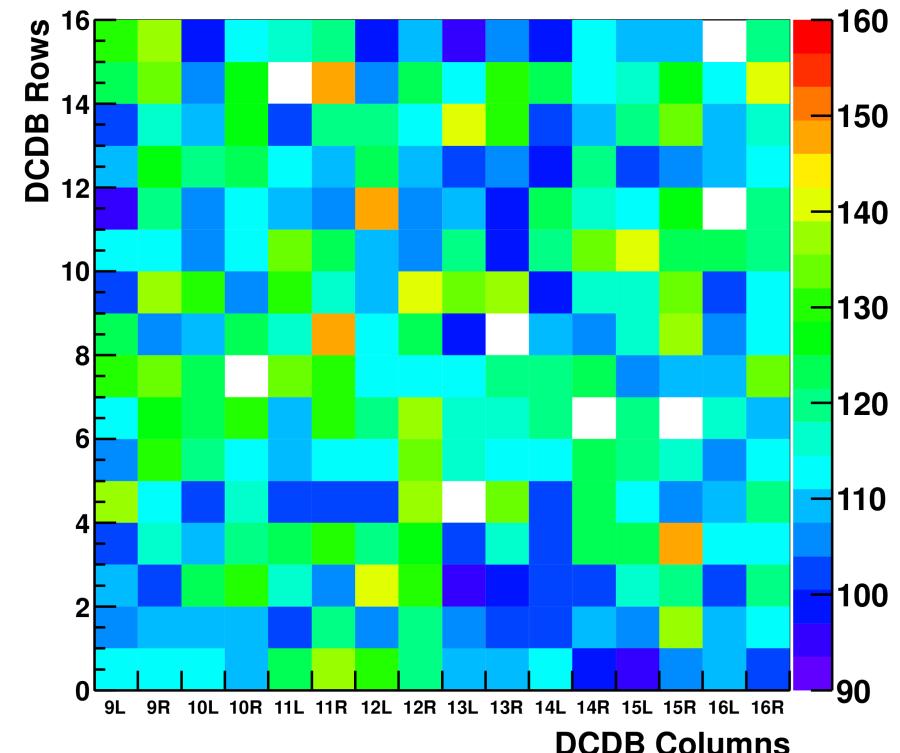
→ Fits to at least 6 of the broken ADCs of the Golden Module.

# The DCDBv1's Current Performance (2/5)

Golden Module: Mean Noise of All ADCs



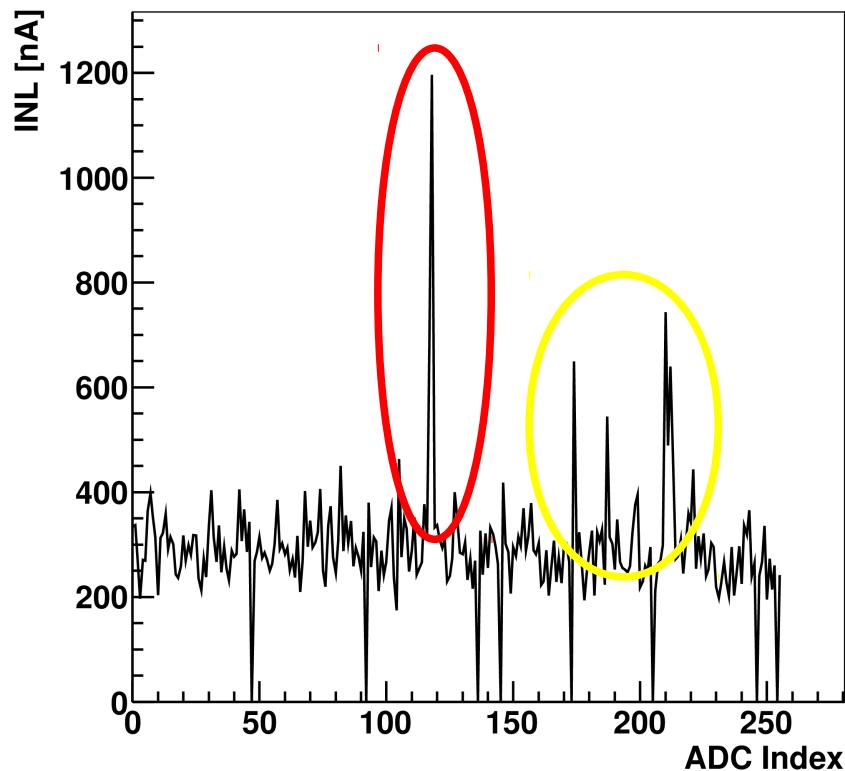
Golden Module: Mean Noise vs. ADC Position



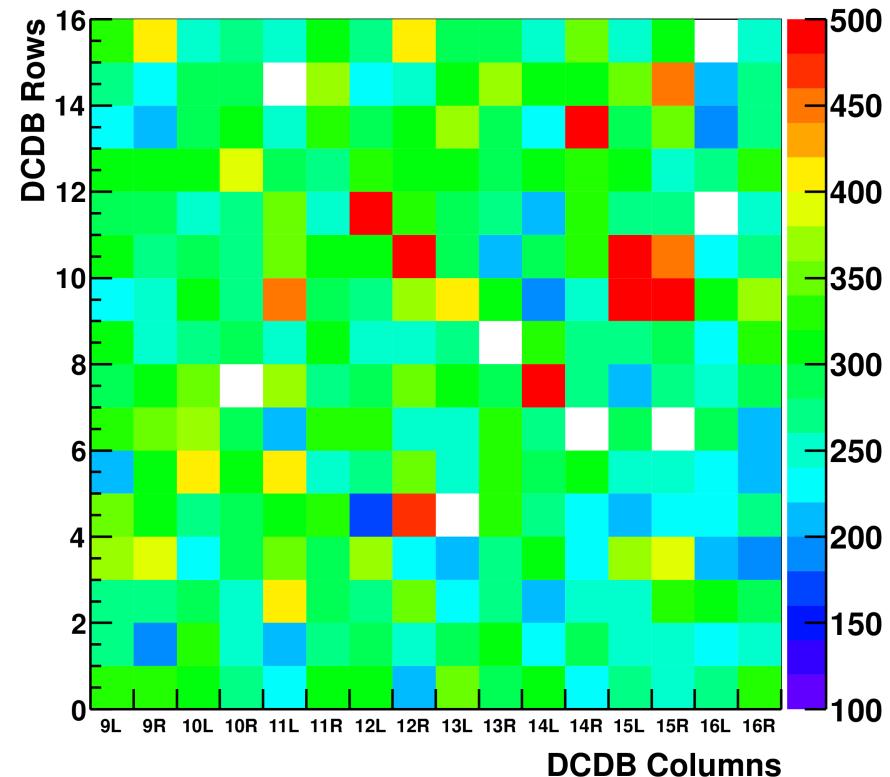
- Mean ADC noise is homogeneous all over the chip.
- Main source of noise is NOT the ADC but rather the TIA.
  - These numbers are based on 30k TIA feedback resistor.
  - Noise almost halves with 60k!

# The DCDBv1's Current Performance (3/5)

Golden Module: Peak-to-Peak INL of All ADCs



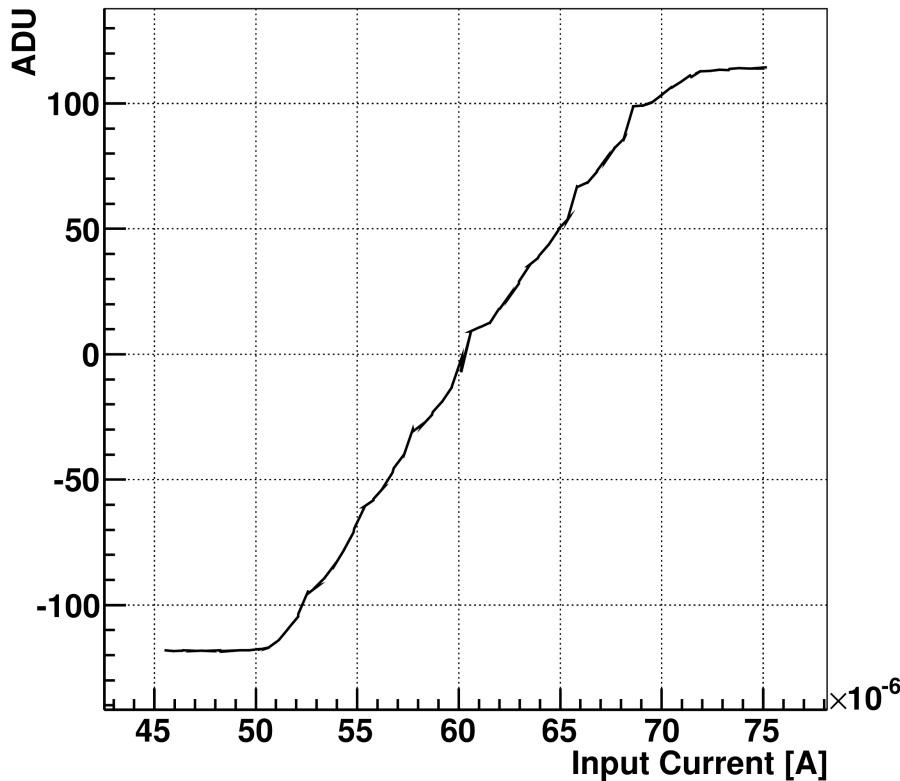
Golden Module: Peak-to-Peak INL vs. ADC Position



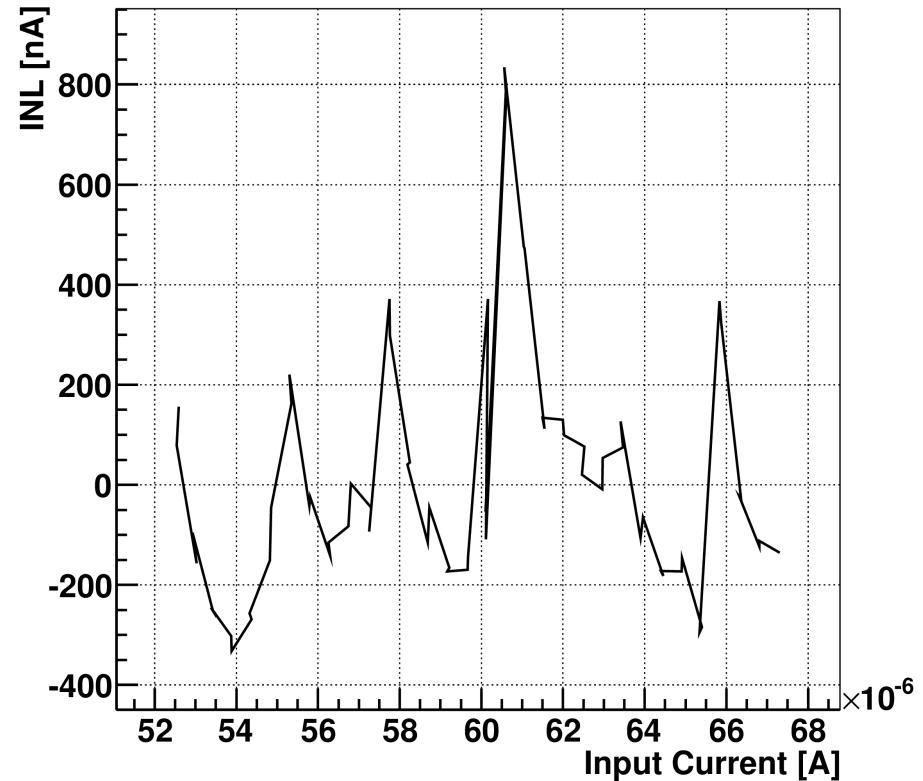
- Integral non-linearity (**peak-to-peak**) is roughly in the order of 2x noise.
- Homogeneous distribution over the chip.
- ~5 ADCs with fairly increased non-linearity. (→ next slide)

# The DCDBv1's Current Performance (4/5)

Golden Module: ADC with worst INL (A3<27>L)



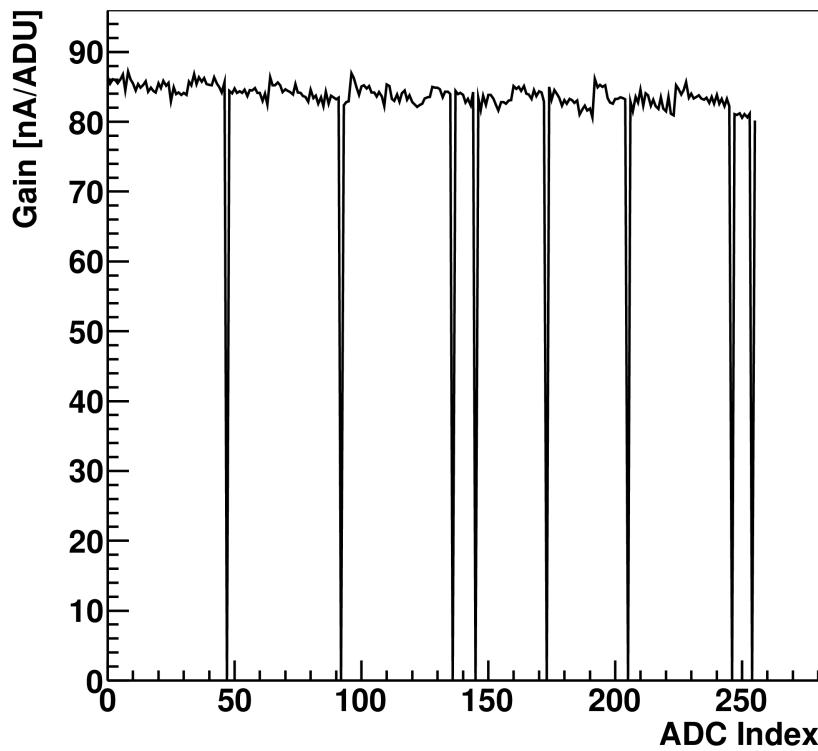
Golden Module: INL of ADC A3<27>L



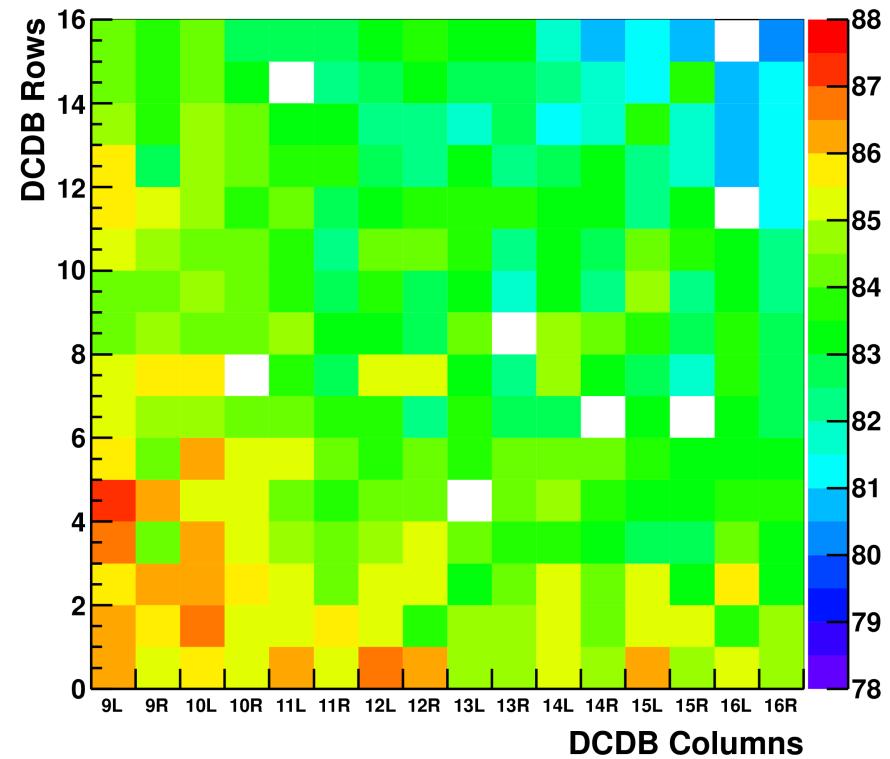
- Non-linearity is caused by steps in the ADC's transfer curve.
- Could be another yield issue.

# The DCDBv1's Current Performance (5/5)

Golden Module: Gain of All ADCs



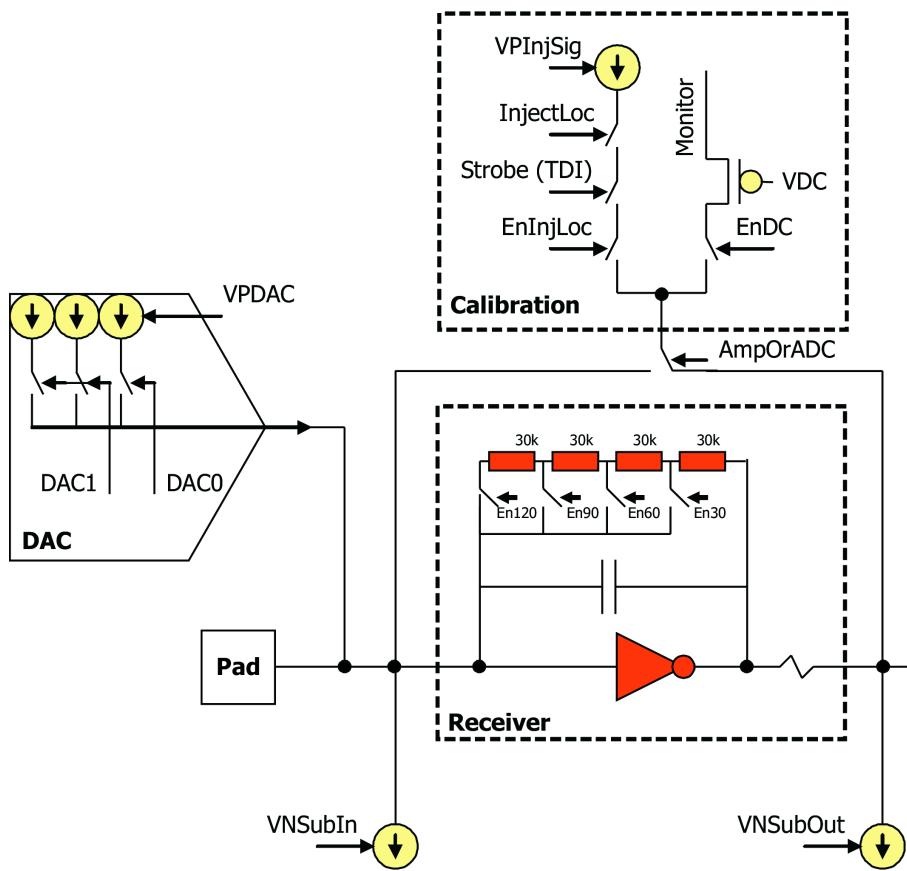
Golden Module: Gain vs. ADC Position



- Gain for applied bias settings and 30k TIA feedback resistor:  $\sim 84\text{nA/ADU}$
- There are two clear but quantitatively small gradients!
  - Vertical gradient might be on-chip voltage drop.
  - The reason for the horizontal gradient is unknown. (Chip layout is symmetrical!)

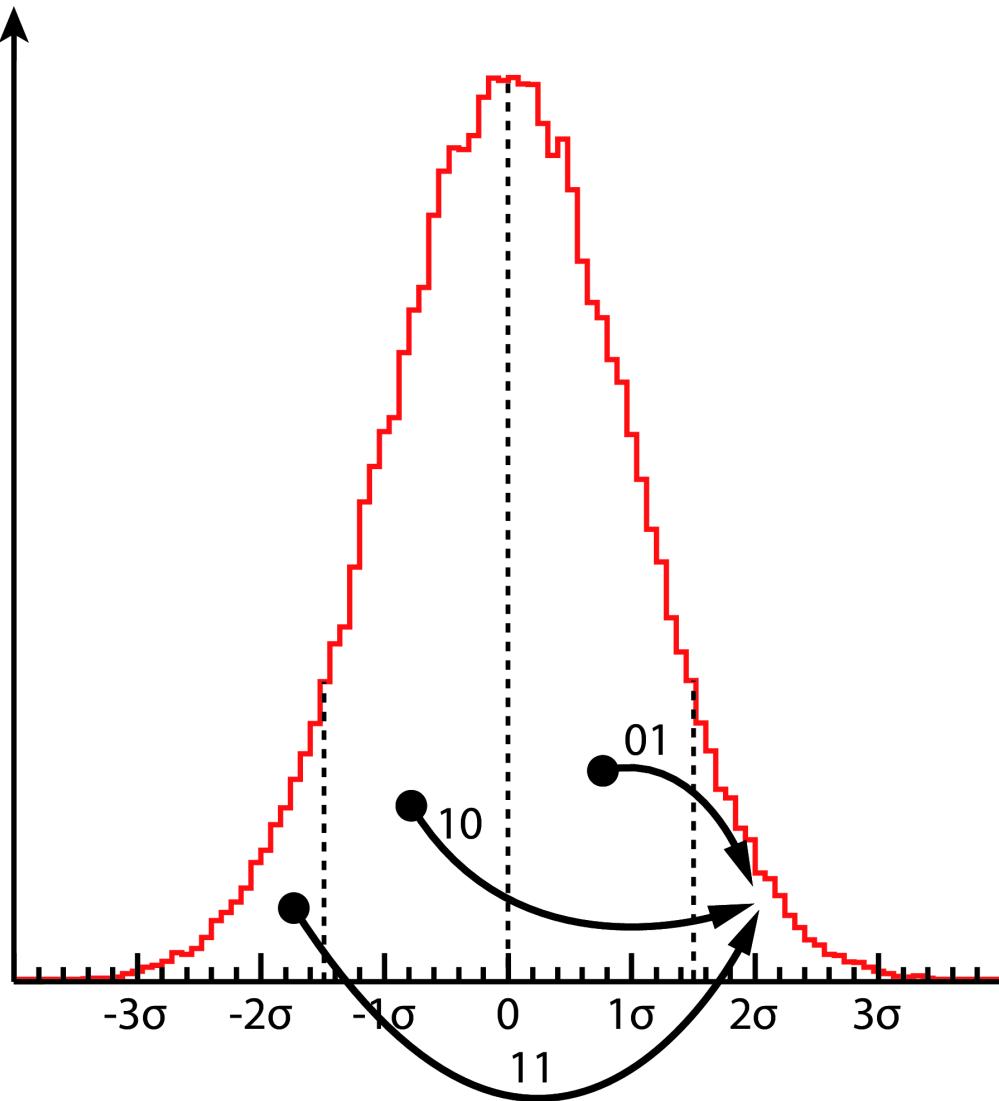
# Part II: DCDB in DEPFET Readout Operation - Dynamic Offset Compensation

# Dynamic Offset Compensation – Principle of Operation



- **Current is dynamically added (!) to the input signal from the DEPFET.**
  - ▶ The lower the pixel's offset, the more current is added.
- **Technical realization:** There are three identical sources, each constantly delivering a unit of current. An additional 2bit factor defines the multiplication between 0x and 3x.
- **Parameters to define:**
  - a) Unit current (per chip)
  - b) Multiplication factor: 0-3 (per matrix pixel)

# Expected Influence on Measurements (1/2)



## Strategy:

*“Bring the effective offsets of all pixels into the uppermost bin.”*

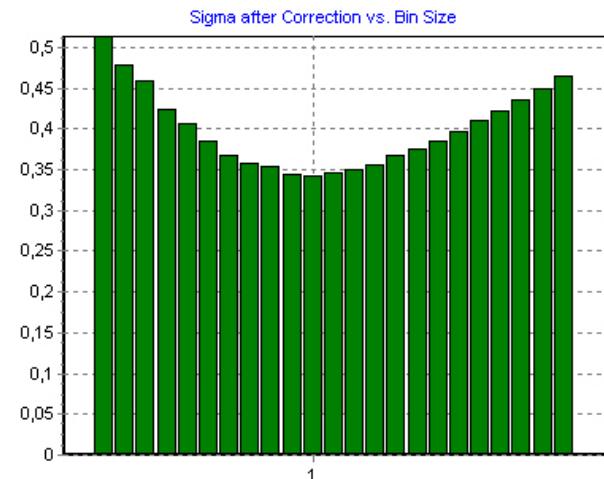
## Question:

*How to set the bins?*

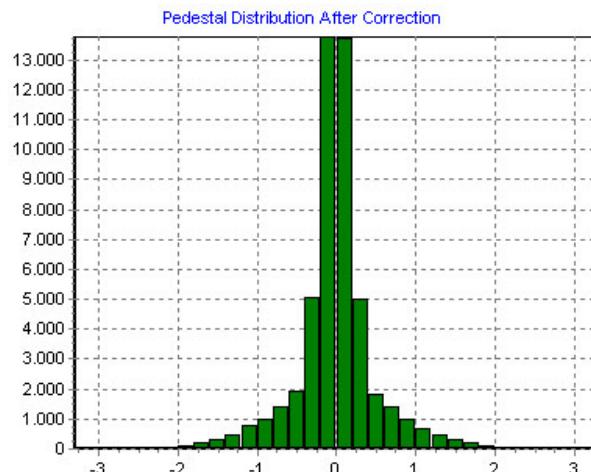
# Expected Influence on Measurements (2/2)

## Simulation:

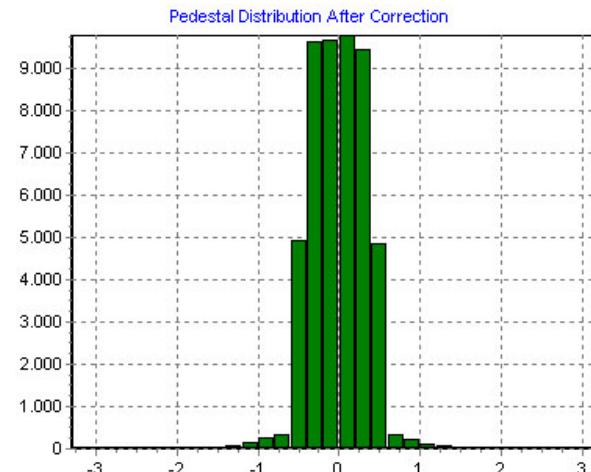
- Assuming uncorrected pedestal distribution with  $\sigma = 1$
- Perform correction based on bin sizes between  $0.5\sigma$  and  $1.6\sigma$
- Calculate  $\sigma$  of resulting corrected distribution



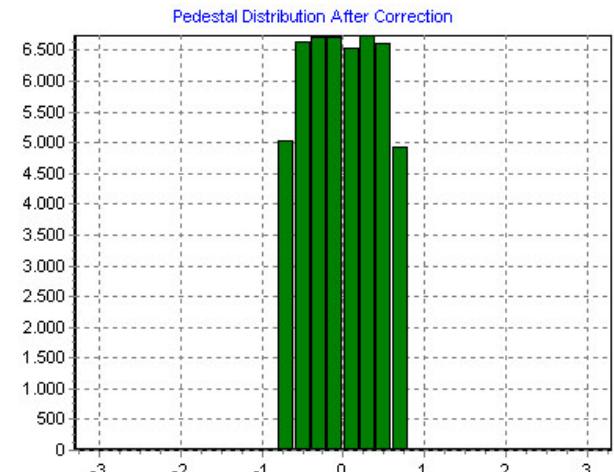
Bin:  $0.5\sigma$



Bin:  $1.0\sigma$



Bin  $1.5\sigma$



Corrected Distribution:

$$\sigma = 0.51$$

$$\sigma = 0.34$$

$$\sigma = 0.44$$

# The Optimization Algorithm

I. Scan: Measure ADU for every combination of

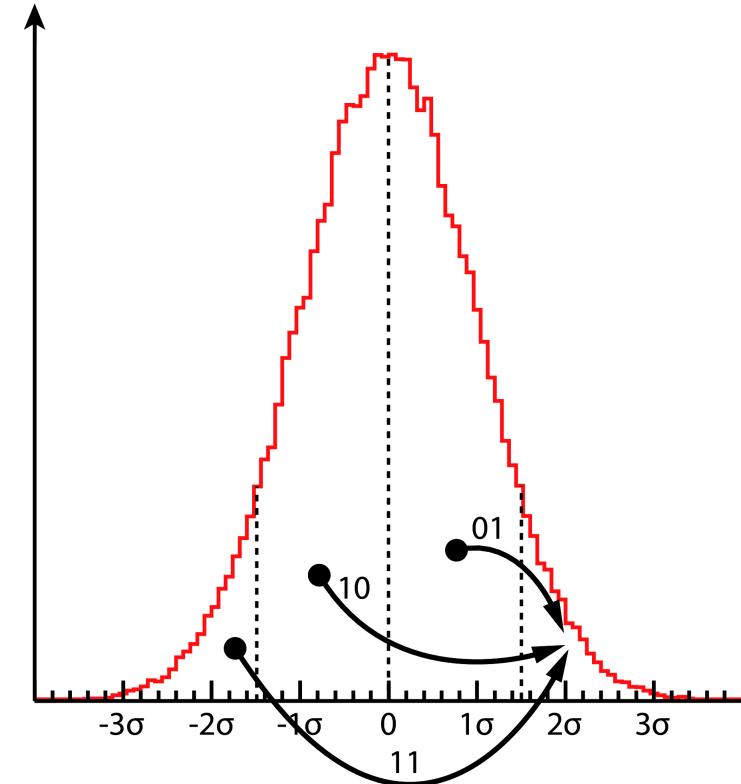
- a) Matrix pixel
  - b) Unit current
  - c) Multiplication factor
- Brute force algorithm  
→ DC Measurements

II. Calculate  $\sigma$  for raw distribution  
(= correction off)

III. Define bin width

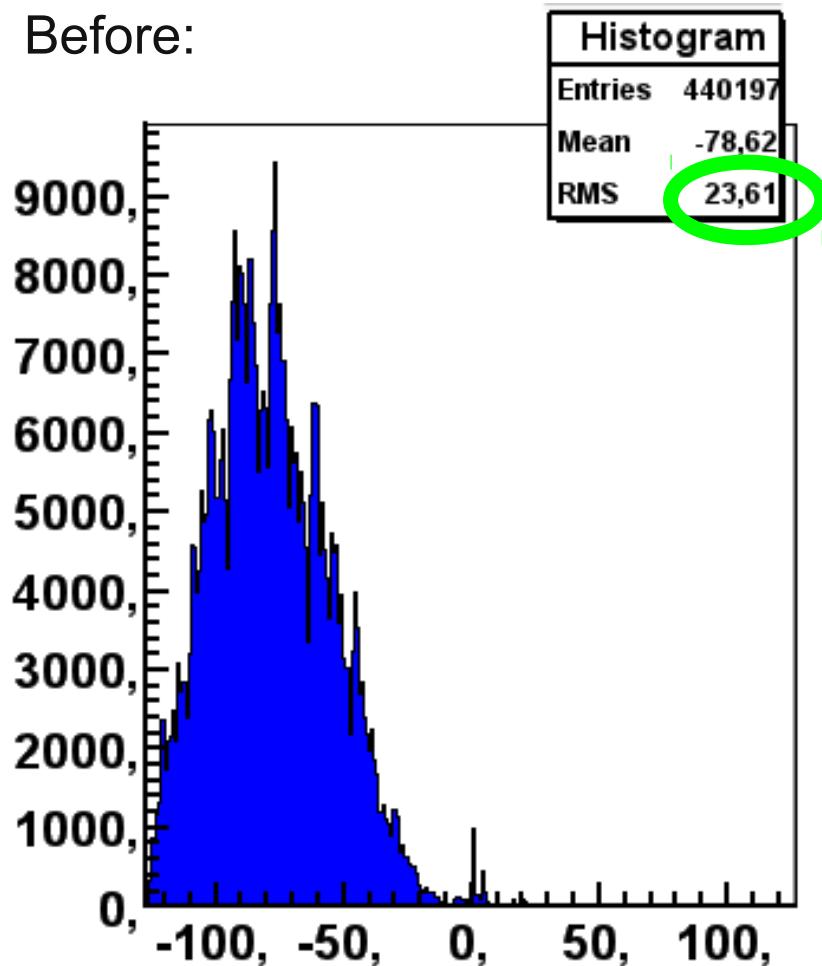
IV. Find best multiplication factor map for each unit current

V. Pick unit current with lowest remaining  $\sigma$

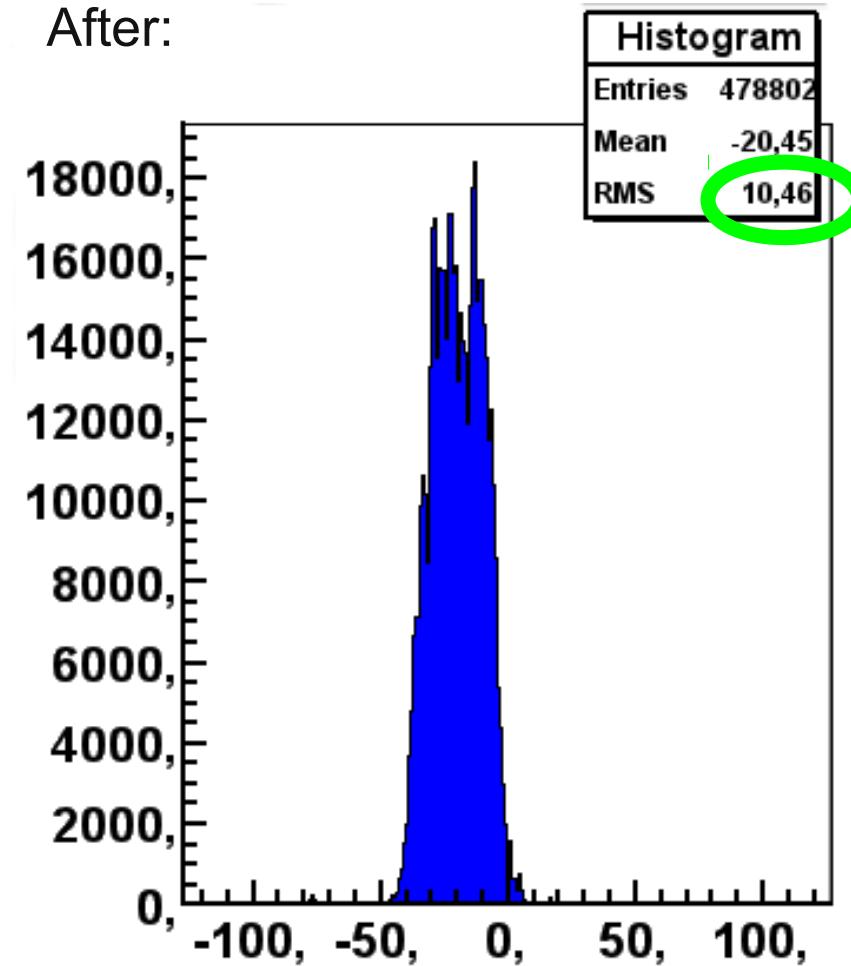


# Dynamic Offset Compensation – The Results

Before:



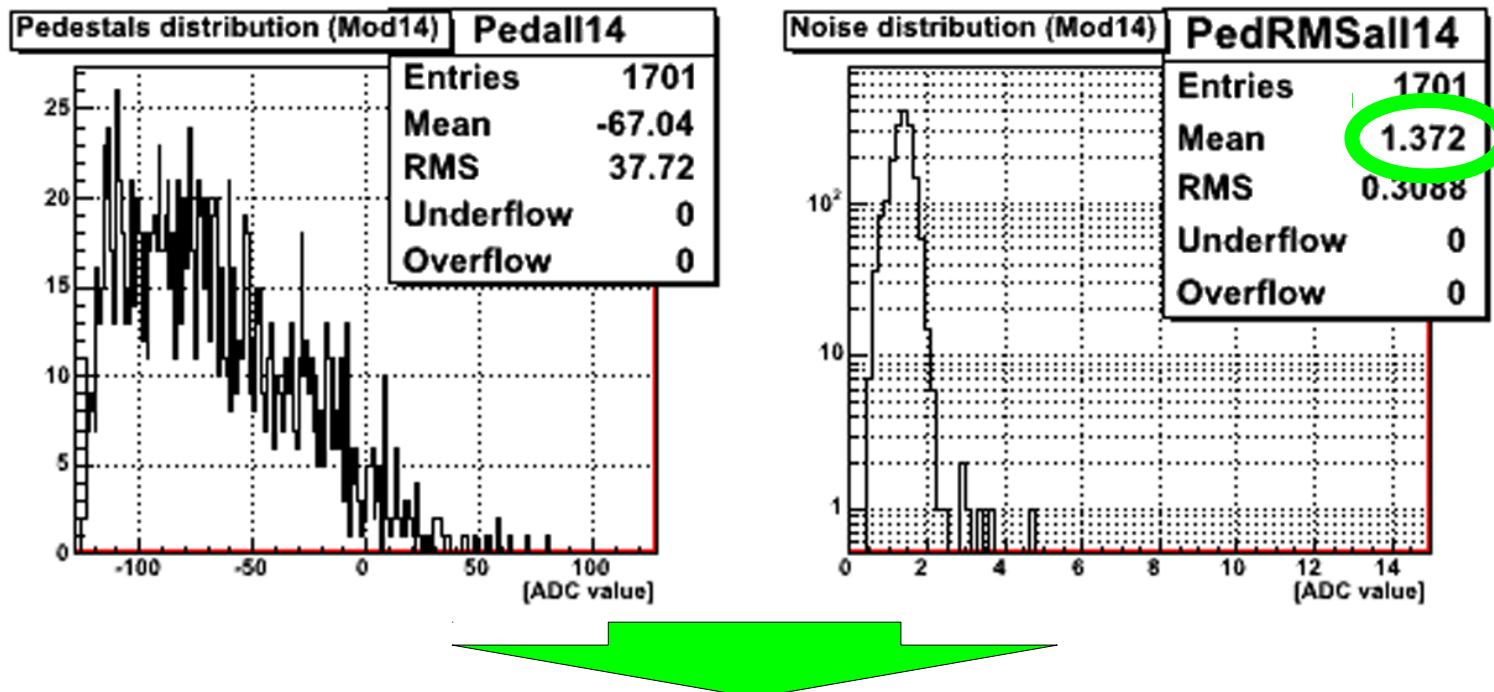
After:



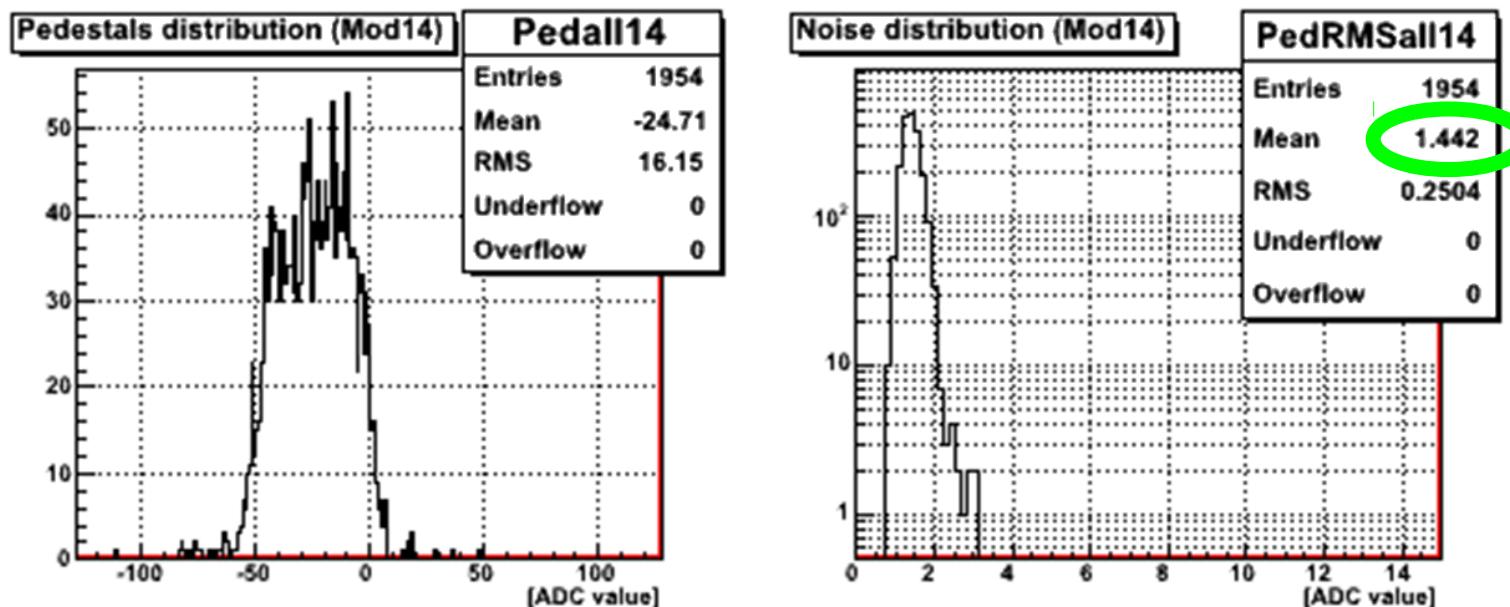
- Same settings and speed as for the DCDB characterization (100ns).
- Here: Bin width =  $1.5\sigma$  → Expected reduction = 44%, Measured reduction = 44.3%
- → **Indirect prove of TIAs dynamic performance!**

# What About the Noise Introduced by Dynamic Offset Compensation?

Before:



After:

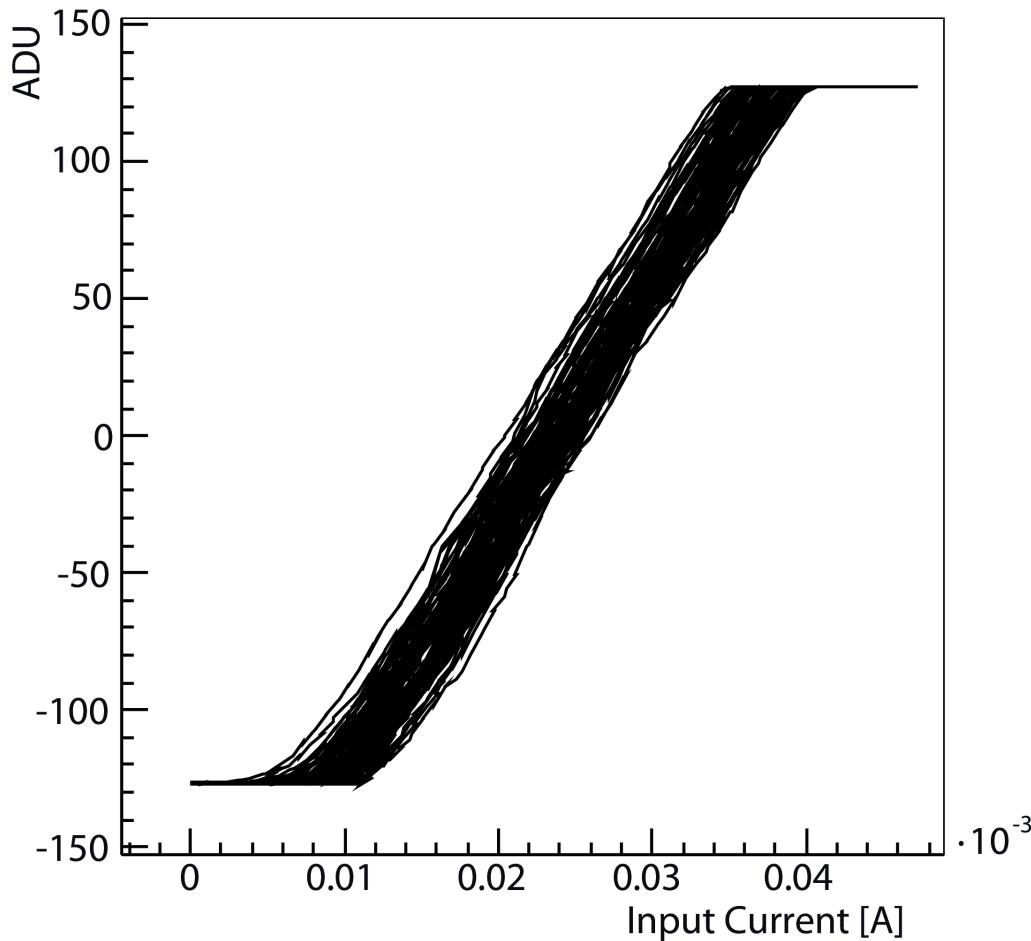


# Part III: DCDB-TC Measurement Results

- Why did we submit a DCDB test chip at all?
  - Because we thought the DCDBv1 would have serious issues...
- Major changes / improvements in DCDB-TC
  - 32 Channels only, standard technology without bumps
    - smaller & cheaper, faster production
  - Delay bias generator was made stronger
  - Separate bulk potential for switch transistors
  - *Modified ADC switches: Low-V<sub>t</sub> transistors used*
  - Input subtraction source doubled (VNSubIn)
  - Internal voltage drops measurable
- Production details:
  - Developed & submitted in October 2010
  - Expected delivery ~Jan 2011, the chip arrived end of Feb 2011!
    - Only very few days of testing before DCDBv2 submission!

# DCDB-TC Measurement Results (1/3)

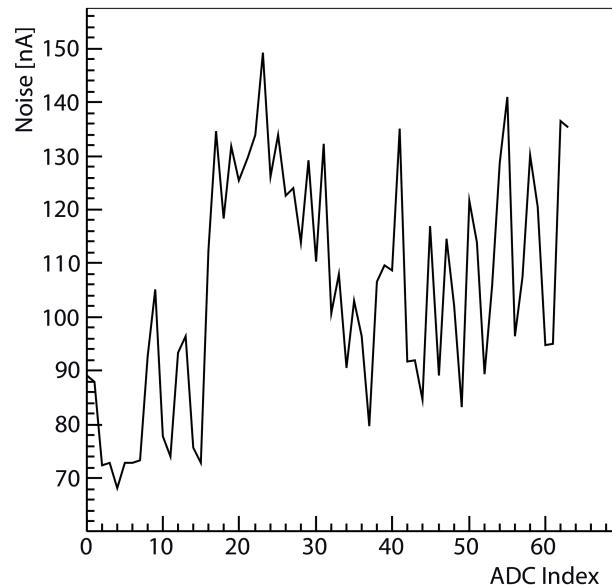
DCDB-TC: Transfer Curves of all ADCs



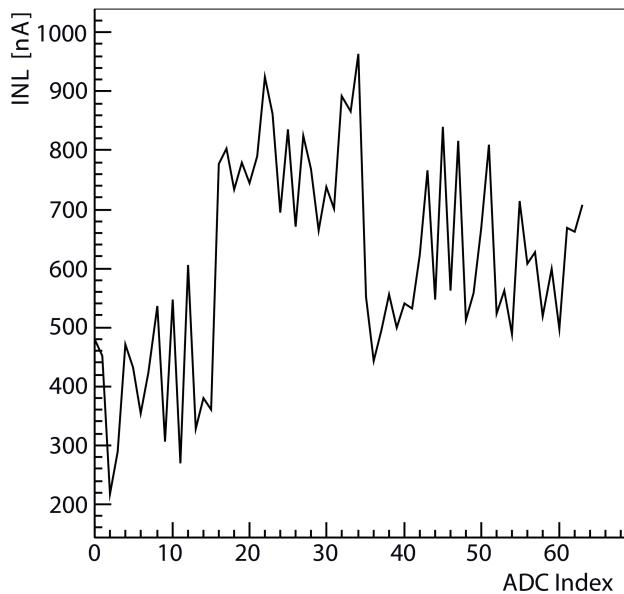
- Operation speed: 400MHz  
→ **80ns** sampling rate
- Internal signal source,  
calibrated via SMU
- Each point is the  
mean of 100 samples
- Vertical dispersion:  
53 ADUs

# DCDB-TC Measurement Results (2/3)

DCDB-TC: Mean Noise of All ADCs

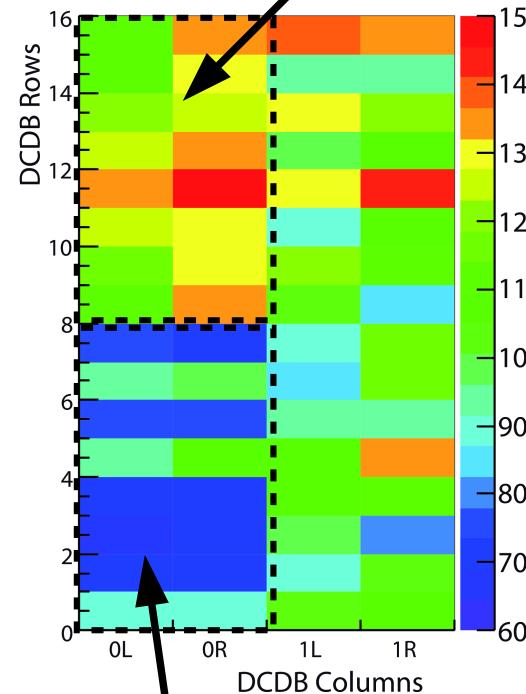


DCDB-TC: Peak-to-Peak INL of All ADCs

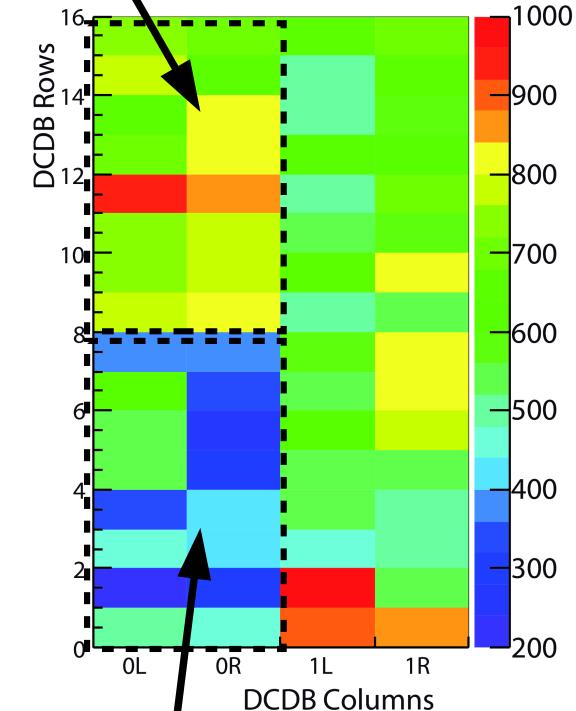


Like DCDBv1

DCDB-TC: Mean Noise vs. ADC Position



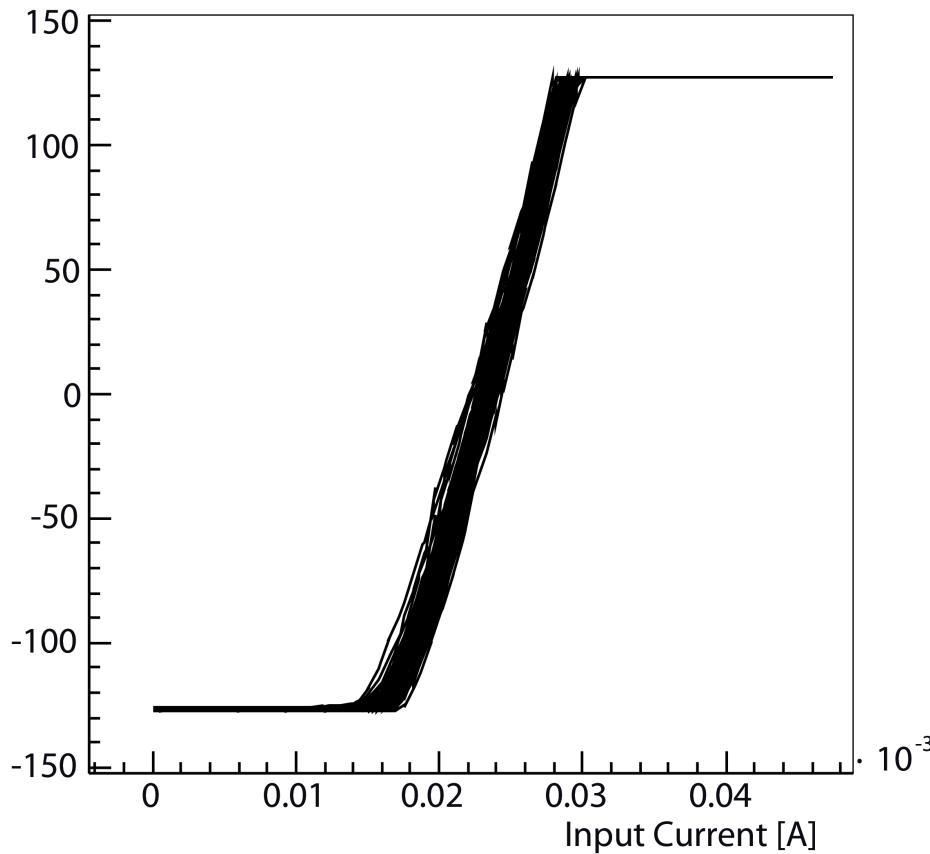
DCDB-TC: Peak-to-Peak INL vs. ADC Position



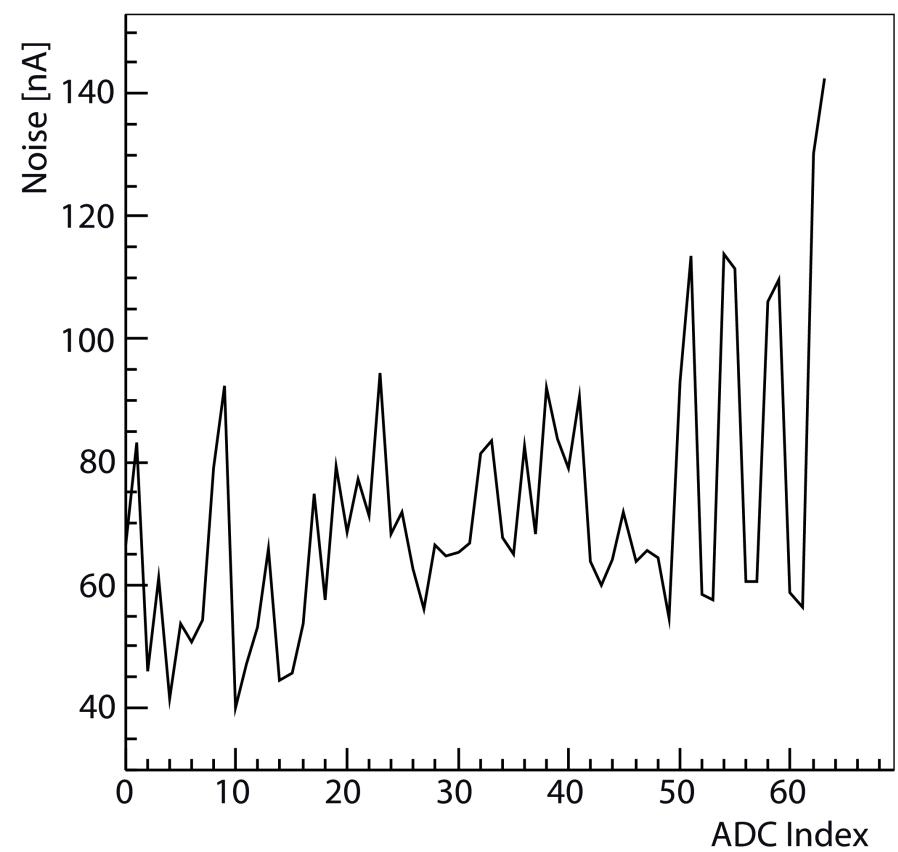
This implementation is used for DCDBv2

# DCDB-TC Measurement Results (3/3)

DCDB-TC: Transfer Curves of all ADCs



DCDB-TC: Mean Noise of All ADCs



Here:  $60\text{k}\Omega$  TIA feedback resistor  
→ Smaller dynamic range but better noise performance.

# Summary

- DCDB-TC measurements
  - Improvements in noise and linearity
  - DCDBv2 (next full size chip) benefits from this achievement.
- Dynamic Offset Compensation
  - Characterization algorithm exists
  - Measured reduction fits perfectly to the expectations
  - Noise performance is not influenced
- Latest DCDBv1 performance measurements @ lowest TIA amplification:
  - 100ns sampling rate
  - ~115nA mean noise
  - ~270nA non-linearity (peak-to-peak!)
  - ~22uA dynamic range



**No magic or fundamental fixes!**  
**The DCDBv1 has been working ever since!**

Thank you!